

## REMARKS

The Examiner is thanked for the thorough examination and search of the subject.

- 5 In regards to the Title, Applicants have amended the Title to "CIRCUITRY COMPONENT WITH DIE AND PASSIVE DEVICE" to limit the focus to the claimed invention. Applicants respectfully request that this title be entered by amendment.

- 10 Claims 231-237, 239, 240, 243-279 are pending. Claims 231-237, 239, 240, 243-279 have been currently amended; Claims 1-230, 238, 241, 242 and 280-319 have been canceled.

### Response to Objection

- 15 *Reconsideration of drawings objected to under 37 CFR 1.83(a) is requested in accordance with the following remarks.*

- 20 The recitation of "a passive device" in claims 231-240 and 243-279 is shown in Figs. 6 and 7 and indicated by a reference number of "644". The recitation of "die portion" in claims 261-263 is amended to "portion", and shown in Fig. 8. The recitation of "an insulating layer over said passive device" in claims 255-258 is shown in Figs. 6 and 7. Withdrawal of the objection is respectfully requested.

### Response to Claim Rejections under 35 U.S.C. 112

- 25 *Reconsideration of claims 261-263 rejected under 35 U.S.C. 112, second paragraph, as being indefinite is requested in accordance with the amendment to claims 261-263.*

With regards to claims 261-263, "said die portion" is amended to "said portion" to meet the requirement of antecedent basis.

Reconsideration of claim 277 rejected under 35 U.S.C. 112, second paragraph, as being indefinite is requested in accordance with the amendment to claim 277.

With regards to claim 277, said passive device is over said horizontal level, at which a top surface of said die exists, but not over said die, as shown in Figs. 6 and 7.

**Response to Claim Rejections under 35 U.S.C. 102 and 103**

Applicants respectfully traverse the rejections for at least the reasons set forth below.

**Response to Claims 231-237, 239, 240, 243-279**

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As currently amended, independent claim 231 is recited below:

231. A circuitry component comprising:

a first die having a top surface at a horizontal level;

a bottommost metal layer over said horizontal level and extending to a place not over said first die, wherein said bottommost metal layer is connected to said first die; and

a passive device over said horizontal level.

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**Section I**

Reconsideration of Claims 231, 232, 239-240, 243, 247, 251, 259-260, 264-265, 267-272 and 278-279 rejected under 35 U.S.C. 102(b) as being anticipated by

*Eichelberger (US6,159,767), and of Claims 233-237, 244-246, 248-250, 252-254 and 266 rejected under 35 U.S.C. 103(a) as being unpatentable over Eichelberger (US6,159,767) in view of Foster et al. (US6,603,072) and/or Yuyuma et al. (US6,620,513), and of Claims 261-263 and 273-276 rejected under 35 U.S.C. 103(a) as being unpatentable over*  
5 *Eichelberger (US6,159,767) is requested in accordance with the following remarks.*

Applicants respectfully assert that the electronic component claimed in claim 231 patentably distinguishes over the citations by Eichelberger (US 6,159,767).

10 Eichelberger teaches a circuitry component comprising a die 102 having a top surface at a horizontal level; a bottommost metal layer over said horizontal level and extending to a place not over said die 102, wherein said bottommost metal layer is connected to said die 102; and an electronic device 220 over said horizontal level. ~ See Fig. 6 and lines 11-17, col. 12 ~

15 In the Examiner's opinion, Eichelberger teaches the electronic device 220 comprises a capacitor or a resistor based on the reference of col. 8, lines 62+ and col. 9, lines 1+. ~ See lines 6-7 in the second paragraph, in page 4, in the last Office Action mailed Jan. 19, 2006 ~

20 Applicants respectfully traverse the Examiner's opinion. In the reference of col. 8, lines 62+ and col. 9, lines 1+, Eichelberger teaches the chips 102 may comprise a capacitor chip or a resistor chip, but fail to teach the electronic device 220 may comprise a capacitor chip or a resistor chip. As a result, Applicants consider that Eichelberger fails to  
25 teach, hint or suggest that a passive can be over said horizontal level, which is claimed in claim 131.

For at least the foregoing reasons, applicants respectfully submit independent claim 231 patentably distinguishes over the prior art references, and should be allowed. For at

least the same reasons, dependent claims 232-237, 239, 240, and 243-279 patently define over the prior art as well.

## Section II

5        *Reconsideration of Claims 231, 232, 236, 239-240, 243-244, 247-248, 251-252, 255-256, 259-260, 264, 271-272 and 277-279 rejected under 35 U.S.C. 102(b) as being anticipated by Saia et al (US5,874,770), and of Claims 261-263 and 274-276 rejected under 35 U.S.C. 103(a) as being unpatentable over Saia et al (US5,874,770) is requested in accordance with the following remarks.*

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Applicants respectfully assert that the electronic component claimed in claim 231 patentably distinguishes over the citations by Saia et al (US 5,874,770).

15        Saia et al teach a circuitry component comprising a die 44 having a top surface at a horizontal level; a bottommost metal layer 33 and 38 over said horizontal level and extending to a place not over said die 44; and a passive device 28, 33 or 37 over said horizontal level. ~See Figs. 7-12 and lines 47-49, col. 6 ~

20        In the Examiner's opinion, reference numbers 47, 48 and 52 indicate the bottommost metal layer. However, Saia et al fail to teach, hint or suggest that reference numbers 47, 48 and 52 may be a metal layer, but teach reference numbers 47, 48 and 52 are vias. ~See Fig.11 and lines 39-44, col. 7 ~ "Via" is typically well-known as a body extending in a substantially vertical direction. "Layer" is typically well-known as a body like a film. A via is usually used to connect the neighboring metal layers. The wordings  
25        of "Via" and "Layer" does not make those skilled in the art confused.

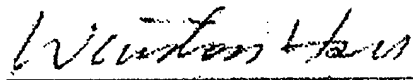
As a result, Applicants consider that Eichelberger fails to teach, hint or suggest that the bottommost metal layer 33 and 38 can be connected to said die 44, which is claimed in claim 231.

For at least the foregoing reasons, applicants respectfully submit independent claim 231 patentably distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent claims 232-237, 239, 240, and 243-279 patentably define  
5 over the prior art as well.

### CONCLUSION

Some or all of the pending claims are believed to be in condition for Allowance,  
10 and that is so requested.

Sincerely yours,



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